HIGH-FLEX™ CONDUCTIVE FABRIC TAPES

Laird High-Flex™ Conductive Fabric Tapes offer exceptional conformability and conductivity for dynamic flex applications. It is constructed of nickel/copper metallized fabric with a conductive pressure sensitive adhesive (PSA). This reliable tape design provides outstanding shielding performance while offering superior abrasion and corrosion resistance under high dynamic flex conditions.

Laird High-Flex™ Conductive Fabric Tapes are halogen free products and can be supplied in tape or further customized to application by die-cutting or hole punching.

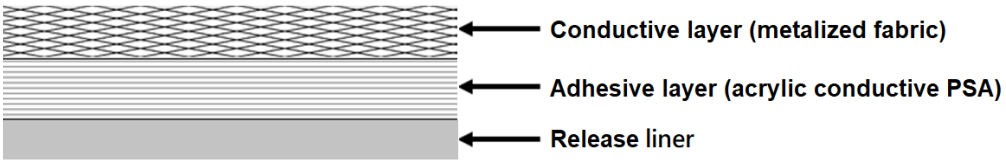
FEATURES

- Shielding effectiveness of >60 dB across a wide spectrum of frequencies RoHS compliant
- Halogen-free per IEC-61249-2-21 standard
- Low surface resistivity provides excellent conductivity
- Shielding effectiveness of >62 dB across a wide spectrum of frequencies

APPLICATIONS

- Cabinet applications
- Displays
- Medical equipment
- Servers
- Desktop/laptop computers
- Telecommunications cabinets

COMPOSITION



CHARACTERISTICS

ITEM	UNIT	Value						TEST METHOD
		85785	86750	86748	81720	87580	1A	
Fabric^	-	PTAF	PTAF	PTAF	PTAF	PTAF	NRS	
Thickness	mm	0.12	0.075	0.060	0.027	0.13	0.15	-
Peel Adhesion	N/25 mm	>11	>9	>11	>8	>8	>10	PSTC 101*
Shear Adhesion at R.T.	Hrs	>168	>24	>24	>72	>72	>24	PSTC 107#
Tensile Strength	Kgf/25 mm	>12	>7	>6	>7	>6	>6	-
Operation Temperature	°C	-40 - 85	-40 - 85	-40 - 85	-40 - 85	-40 - 85	-40 - 85	-
Surface Resistivity (Fabric Side)	Ω/□	<0.05	<0.05	<0.05	<0.05	<0.05	<0.07	ASTM F390
Z-axial Resistance	Ω	<0.04	<0.03	<0.05	<0.05	<0.05	<0.03	-
Flame Retardant	-	n/a	n/a	n/a	n/a	UL510FR	n/a	
Shielding Effectiveness+								ASTM D4935
at 100 MHz	dB	76	68	60	60	75	70	
at 1GHz	dB	82	75	68	66	72	75	
Package Dimensions (Max. Width: 1000 mm)		Width: customized, max. width 1000 mm Length : standard length 20 M.						-
Shelf Life		12 months under 23°C/65% R.H.						-

^: PTAF-polyester taffeta; NRS-Nylon ripstop *:Test Method A, dwell time 30-60min. #:Contact area 25 mm by 25 mm +:Typical value

APPLICATION TECHNIQUES

1. Adhesion is dependent upon the amount of adhesive-to-surface contact developed. Apply normal pressure to the bonding surface will develop better adhesive contact, and thus improve adhesion.
   To a 25mm(1in.) width tape, recommend to use a 2Kgf rubber roller to press back and forth twice under the speed of 5mm/sec. Users may adjust the speed or roller loading according to different application.
   Users may also apply 5psi for 10sec to the surface. The loading and residual time can be adjusted as well according to the application and area.
2. After applying the tape onto a surface, the adhesion will go up gradually.
3. To obtain optimum adhesion, the bonding surfaces must be clean, dry and well unified. A typical surface cleaning solvent is isopropyl alcohol. Use proper safety precautions for handling solvents.
4. Ideal tape application temperature range is 21°C to 38°C. Initial tape application to surfaces at temperatures below 10°C is not recommended because the adhesive becomes too firm to adhere readily. However, once properly applied, low temperature holding is generally satisfactory.

LAIRD PERFORMANCE MATERIALS

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